

KS54AHCT 564
KS74AHCT

Octal D-Type Flip-Flops
with 3-State Outputs

T-46-07-05

FEATURES

- Function, pin-out, speed and drive compatibility with 54/74ALS logic family
- Low power consumption characteristic of CMOS
- 3-State outputs with high drive current ($I_{OL} = 24mA @ V_{OL} = 0.5V$) for direct bus interface
- Inputs and outputs interface directly with TTL, NMOS and CMOS devices
- Wide operating voltage range: 4.5V to 5.5V
- Characterized for operation over industrial and military temperature ranges:
 KS74AHCT: $-40^{\circ}C + 85^{\circ}C$
 KS54AHCT: $-55^{\circ}C + 125^{\circ}C$
- Package options include plastic "small outline" packages, standard plastic and ceramic 300-mil DIPs

DESCRIPTION

The '564' consists of 8 high-speed D-type edge-triggered flip-flops coupled to 3-state output buffers with high drive current capability. It can be used in implementing buffer registers, I/O ports, bidirectional bus driver and working registers.

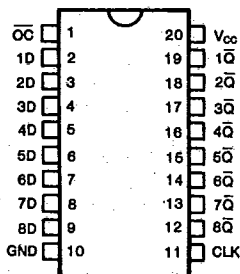
The flip-flops are edge-triggered: on the positive transition of the clock, the \bar{Q} outputs are set to the complement of the logic levels that were set up at the D inputs.

The output buffers are controlled by a common signal (\bar{OC}) which places the outputs at high impedance state when it is taken high. The OC signal does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while outputs are off.

These devices provide speeds and drive capability equivalent to their ALSTTL counterparts and yet maintain CMOS power levels. The input and output voltage levels allow direct interface with TTL, NMOS and CMOS devices without any external components.

All inputs and outputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

PIN CONFIGURATION

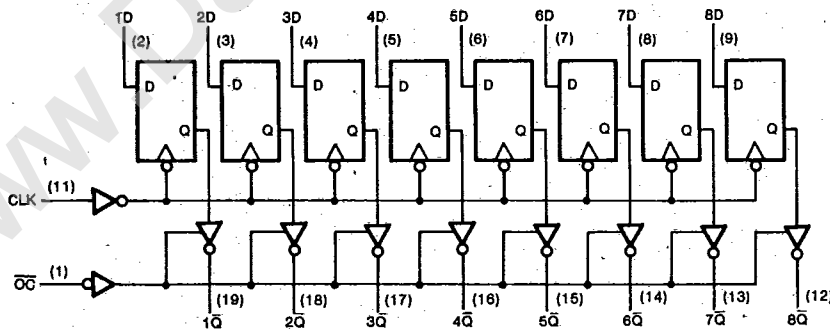


FUNCTION TABLE

(Each Flip-Flop)

Inputs			Output
\bar{OC}	CLK	D	\bar{Q}
L	\uparrow	H	L
L	\uparrow	L	H
L	L	X	Q_0
H	X	X	Z

LOGIC DIAGRAM



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Absolute Maximum Ratings*

Supply Voltage Range V_{CC} -0.5V to +7V
 DC Input Diode Current, I_{IK}
 ($V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$) ± 20 mA
 DC Output Diode Current, I_{OK}
 ($V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$) ± 20 mA
 Continuous Output Current Per Pin, I_O
 ($-0.5V < V_O < V_{CC} + 0.5V$) ± 70 mA
 Continuous Current Through
 V_{CC} or GND pins ± 250 mA
 Storage Temperature Range, T_{stg} -65°C to +150°C
 Power Dissipation Per Package, P_d † 500 mW

* Absolute Maximum Ratings are those values beyond which permanent damage to the device may occur. These are stress ratings only and functional operation of the device at or beyond them is not implied. Long exposure to these conditions may affect device reliability.

† Power Dissipation temperature derating:
 Plastic Package (N): -12mW/°C from 65°C to 85°C
 Ceramic Package (J): -12mW/°C from 100°C to 125°C

Recommended Operating Conditions

Supply Voltage, V_{CC} 4.5V to 5.5V
 DC Input & Output Voltages*, V_{IN} , V_{OUT} . . 0V to V_{CC}
 Operating Temperature
 Range KS74AHCT: -40°C to +85°C
 KS54AHCT: -55°C to +125°C
 Input Rise & Fall Times, t_r , t_f Max 500 ns

* Unused inputs must always be tied to an appropriate logic voltage level (either V_{CC} or GND)

DC ELECTRICAL CHARACTERISTICS ($V_{CC}=5V \pm 10\%$ Unless Otherwise Specified)

Characteristic	Symbol	Test Conditions	$T_a = 25^\circ\text{C}$		KS74AHCT	KS54AHCT	Unit
			Typ	Guaranteed Limits	$T_a = -40^\circ\text{C to } +85^\circ\text{C}$	$T_a = -55^\circ\text{C to } +125^\circ\text{C}$	
Minimum High-Level Input Voltage	V_{IH}			2.0	2.0	2.0	V
Maximum Low-Level Input Voltage	V_{IL}			0.8	0.8	0.8	V
Minimum High-Level Output Voltage	V_{OH}	$V_{IN}=V_{IH}$ or V_{IL} $I_O=-20\mu\text{A}$ $I_O=-6\text{mA}$	V_{CC} 4.2	$V_{CC}-0.1$ 3.98	$V_{CC}-0.1$ 3.84	$V_{CC}-0.1$ 3.7	V
Maximum Low-Level Output Voltage	V_{OL}	$V_{IN}=V_{IH}$ or V_{IL} $I_O=20\mu\text{A}$ $I_O=12\text{mA}$ $I_O=24\text{mA}$	0	0.1 0.26 0.39	0.1 0.33 0.5	0.1 0.4	V
Maximum Input Current	I_{IN}	$V_{IN}=V_{CC}$ or GND		± 0.1	± 1.0	± 1.0	μA
Maximum 3-State Leakage Current	I_{OZ}	Output Enable = V_{IH} $V_{OUT}=V_{CC}$ or GND		± 0.5	± 5.0	± 10.0	μA
Maximum Quiescent Supply Current	I_{CC}	$V_{IN}=V_{CC}$ or GND $I_{OUT}=0\mu\text{A}$		8.0	80.0	160.0	μA
Additional Worst Case Supply Current	ΔI_{CC}	per input pin $V_I=2.4V$ other inputs: at V_{CC} or GND $I_{OUT}=0\mu\text{A}$		2.7	2.9	3.0	mA

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AC ELECTRICAL CHARACTERISTICS (Input $t_r, t_f < 2$ ns), AHCT564

Characteristic	Symbol	Conditions†	$T_a = 25^\circ\text{C}$	KS74AHCT		KS54AHCT		Unit
			$V_{CC} = 5.0\text{V}$	$T_a = -40^\circ\text{C to } +85^\circ\text{C}$ $V_{CC} = 5.0\text{V} \pm 10\%$		$T_a = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = 5.0\text{V} \pm 10\%$		
			Typ	Min	Max	Min	Max	
Maximum Operating Frequency	f_{max}	$C_L = 50\text{pF}$	50	35		30		MHz
Propagation Delay, CLK to any \bar{Q}	t_{PLH}	$C_L = 50\text{pF}$ $C_L = 150\text{pF}$	8 11		14 19		17 23	ns
	t_{PHL}	$C_L = 50\text{pF}$ $C_L = 150\text{pF}$	8 11		14 19		17 23	
Output Enable Time, \bar{OC} to any \bar{Q}	t_{PZH}	$R_L = 1\text{k}\Omega$	$C_L = 50\text{pF}$ $C_L = 150\text{pF}$	11 14		18 23	22 28	ns
	t_{PZL}		$C_L = 50\text{pF}$ $C_L = 150\text{pF}$	11 14		18 23	22 28	
Output Disable Time, \bar{OC} to any \bar{Q}	t_{PHZ}	$R_L = 1\text{k}\Omega$	13		19		22	ns
	t_{PLZ}	$C_L = 50\text{pF}$	13		19		28	
Pulse Width, CLK High or Low	t_w		9	15		18		ns
Setup Time, D before CLK†	t_{su}		9	14		17		ns
Hold Time, D after CLK†	t_h		-3	0		0		ns
Input Capacitance	C_{IN}		5					pF
Output Capacitance	C_{OUT}	Output Disabled	10					pF
Power Dissipation Capacitance* (per stage)	C_{PD}	$\bar{OC} = V_{CC}$	5					pF
		$\bar{OC} = \text{GND}$	30					

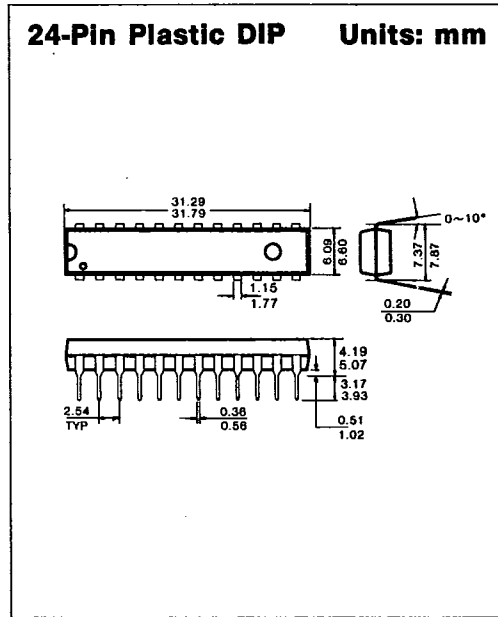
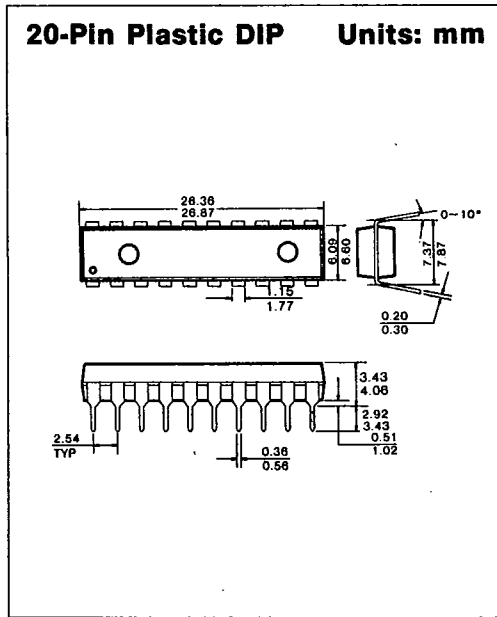
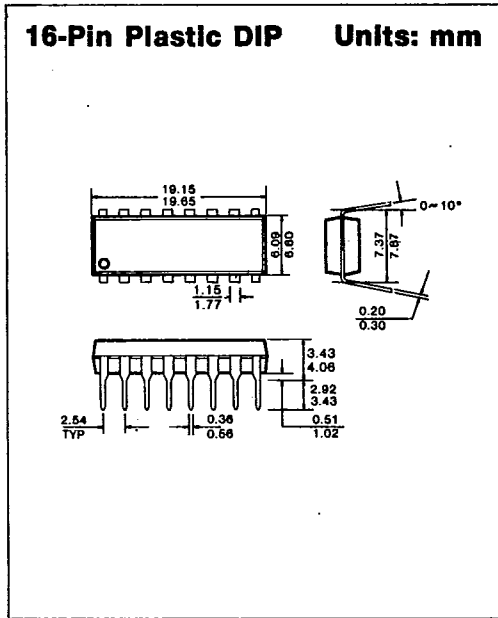
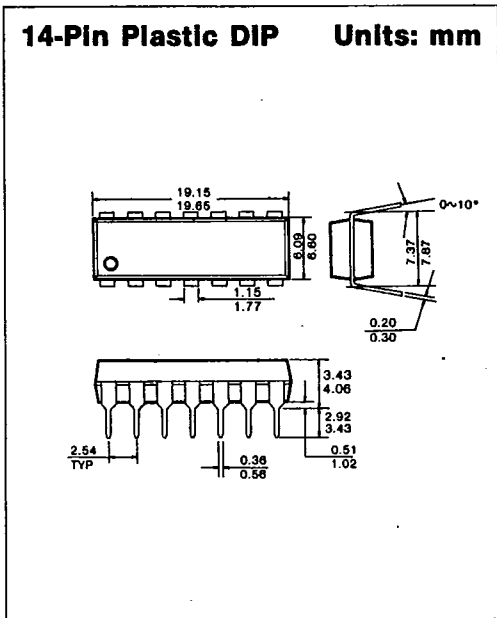
* C_{PD} determines the no-load dynamic power dissipation: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

† For AC switching test circuits and timing waveforms see section 2.

PACKAGE DIMENSIONS

T-90-20

1. PLASTIC PACKAGES



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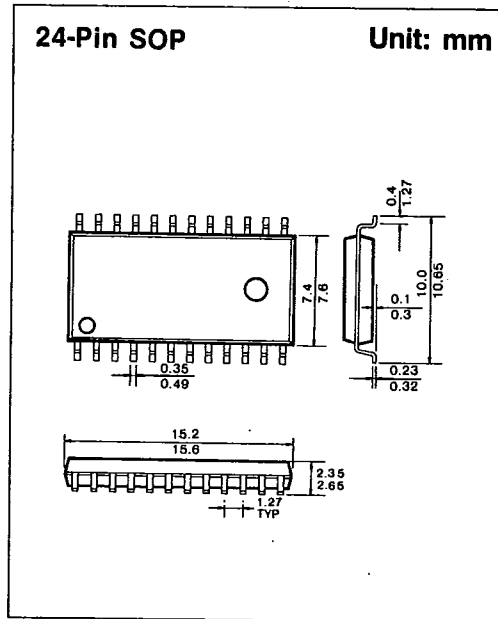
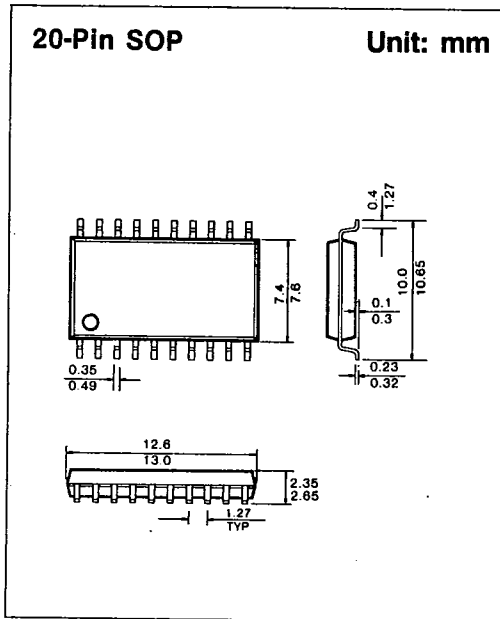
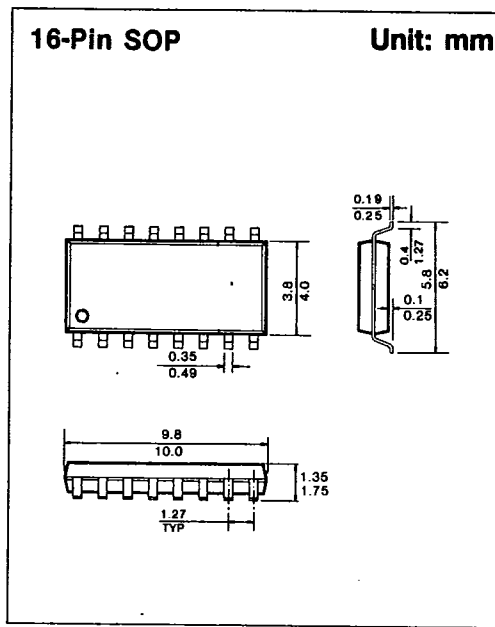
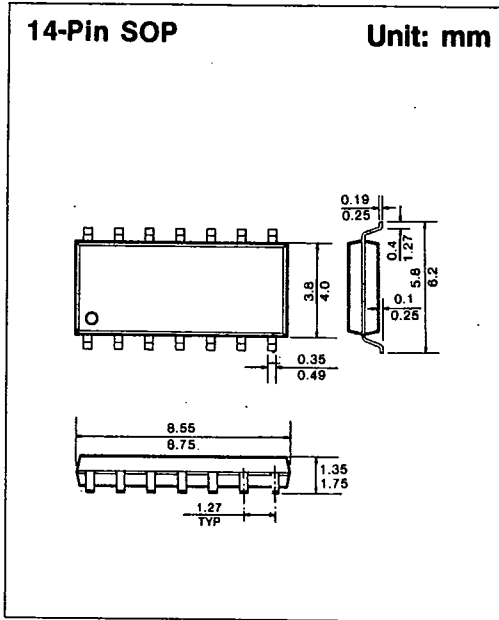
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PACKAGE DIMENSIONS

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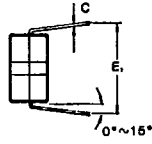
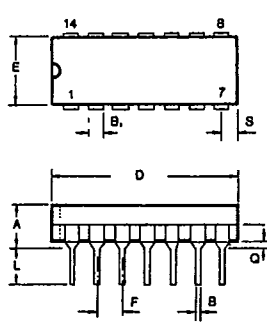


PACKAGE DIMENSIONS

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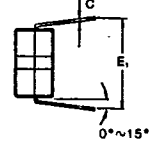
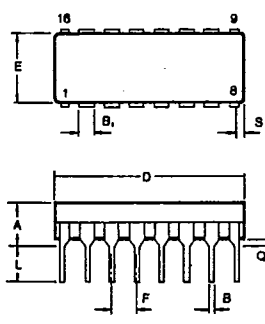
2. CERAMIC PACKAGES

14-Pin Ceramic DIP Units: mm



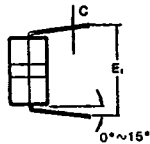
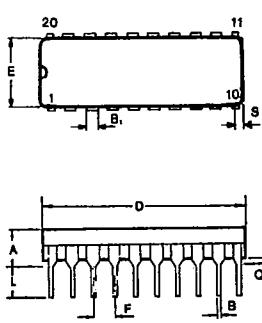
Dim	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	18.16	19.58
E	8.10	7.49
E1	7.62	10.03
F	2.54	
L	3.18	4.19
Q	0.51	1.02
S	1.91	2.29

16-Pin Ceramic DIP Units: mm



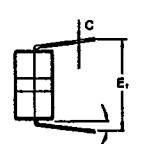
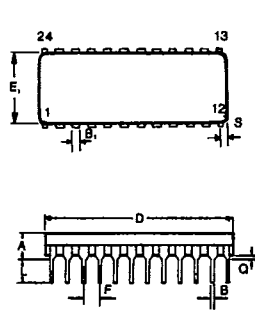
Dim	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	19.05	19.94
E	8.10	7.49
E1	7.62	10.03
F	2.54	
L	3.18	4.19
Q	0.51	1.02
S	0.51	1.14

20-Pin Ceramic DIP Units: mm



Dim	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	25.78	26.93
E	8.10	8.60
E1	7.77	7.88
F	2.54	
L	3.73	4.01
Q	0.38	0.89
S	0.51	1.14

24-Pin Ceramic DIP Units: mm



Dim	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	31.50	32.84
E	7.24	7.75
E1	7.77	7.98
F	2.54	
L	3.73	4.01
Q	0.508	1.778
S	1.85	1.93

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